

RoHS COMPLIANT

HALOGEN

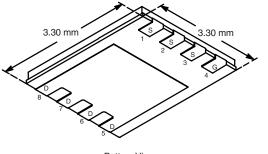
FREE

Vishay Siliconix

N-Channel 12 V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)		
12	0.0057 at V _{GS} = 4.5 V	20		
	0.0067 at V_{GS} = 2.5 V	18.8		
	0.0085 at V _{GS} = 1.8 V	16.5		





Bottom View

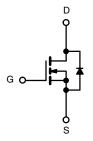
Ordering Information: Si7402DN-T1-E3 (Lead (Pb)-free) Si7402DN-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- New Low Thermal Resistance PowerPAK[®] Package with Low 1.07 mm Profile
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- PA Switch, Load Switch and Battery Switch for Portable Devices
- Point-of-Load for 5 V or 3.3 V BUS Stepdown



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	A = 25 °C, unles	ss otherwise n	oted			
Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage		V _{DS}	12		V	
Gate-Source Voltage		V _{GS}	± 8			
	T _A = 25 °C	– I _D	20	13		
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		16	10		
Pulsed Drain Current		I _{DM}	50		A	
Continuous Source Current (Diode Conduction) ^a		۱ _S	3.2	1.3		
	T _A = 25 °C	– P _D	3.8	1.5	W	
Maximum Power Dissipation ^a	T _A = 70 °C		2.4	1.0		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature) ^{b, c}			260		°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Manimum Lunching to Anglianda	t ≤ 10 s	- R _{thJA} R _{thJC}	24	33		
Maximum Junction-to-Ambient ^a	Steady State		65	81	°C/W	
Maximum Junction-to-Case (Drain)	Steady State		1.9	2.4		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. See Solder Profile (<u>www.vishay.com/ppg?73257</u>). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

c. Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static			•			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	0.45		0.85	V
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V$, $V_{GS} = \pm 8 V$		± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$			1	
		V_{DS} = 12 V, V_{GS} = 0 V, T_{J} = 55 °C			5	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}$	50			А
Drain-Source On-State Resistance ^a		$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$ $V_{GS} = 2.5 \text{ V}, I_D = 18 \text{ A}$		0.0045	0.0057	Ω
	R _{DS(on)}			0.0053	0.0067	
		$V_{GS} = 1.8 \text{ V}, I_D = 10 \text{ A}$		0.0065	0.0085	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 20 \text{ A}$		100		S
Diode Forward Voltage ^a	V _{SD}	$I_{\rm S} = 3.2$ A, $V_{\rm GS} = 0$ V		0.70	1.2	V
Dynamic ^b						
Total Gate Charge	Qg			36	55	
Gate-Source Charge	Q _{gs}	V_{DS} = 6 V, V_{GS} = 4.5 V, I_D = 20 A		4		nC
Gate-Drain Charge	Q _{gd}			9.5		
Gate Resistance	Rg			1.8		Ω
Turn-On Delay Time	t _{d(on)}			35	55	ns
Rise Time	t _r	V_{DD} = 6 V, R_L = 6 Ω		65	100	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong \text{1}$ A, V_GEN = 4.5 V, R_g = 6 Ω		110	165	
Fall Time	t _f			60	90	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 2.3 A, dl/dt = 100 A/μs		40	80	

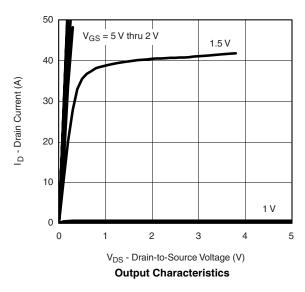
Notes:

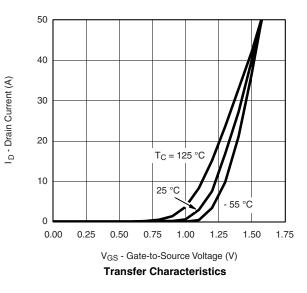
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



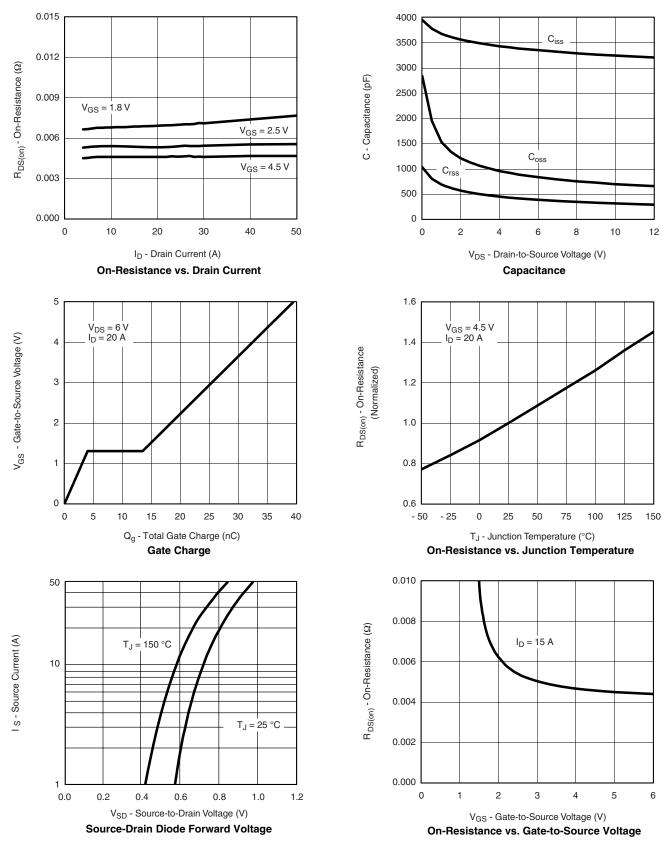




Si7402DN

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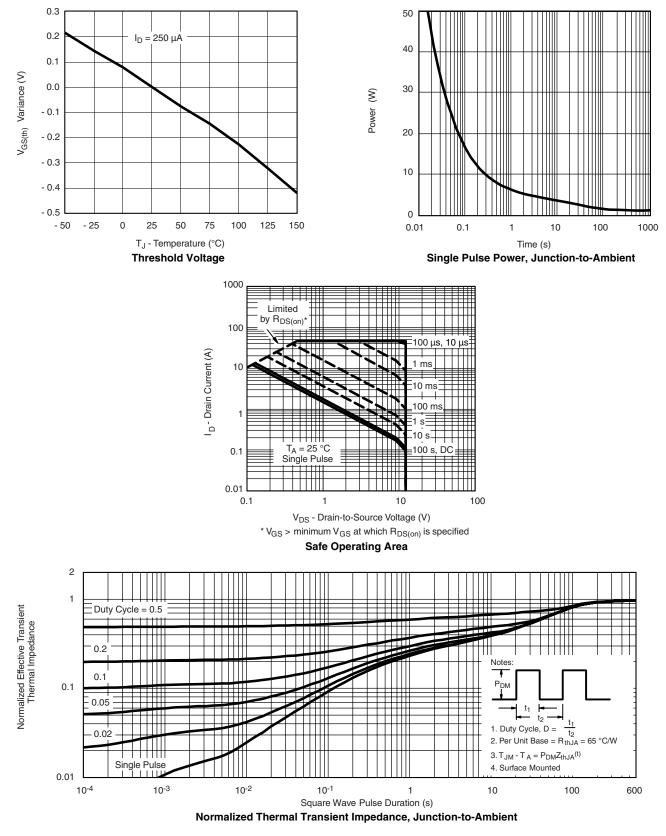
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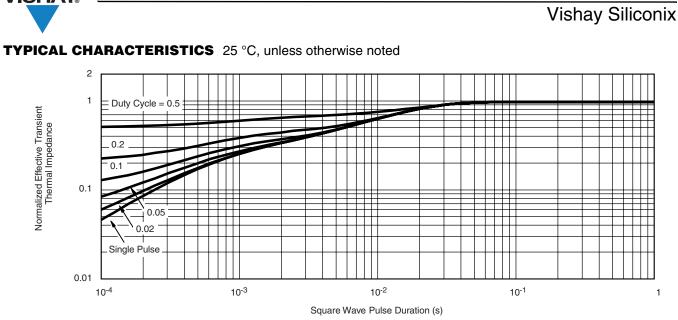
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/ISHA



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <u>www.vishay.com/ppg772646</u>.

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